

# SN54AS890, SN74AS890 MICROSEQUENCERS

D2662, NOVEMBER 1982—REVISED APRIL 1985

- 14 Bits Wide—Addresses up to 16,384 Words of Microcode with One Chip
- Selects Address from One of Eight Sources
- STL-AS Technology
- Independent Read Pointer for Aid in Microcode Diagnostics
- Supports Real-Time Interrupts
- Two Independent Loop Counters
- Supports 64 Powerful Instructions
- Dependable Texas Instruments Quality and Reliability

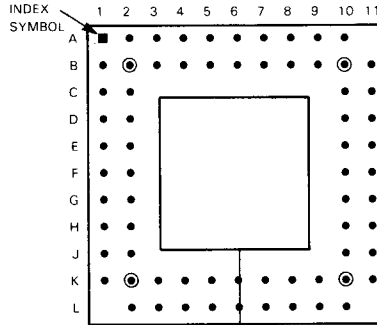
## description

The 'AS890 is a powerful microsequencer that is the result of the implementation of TI's Advanced Schottky and Schottky Transistor Logic. Approximately 2400 Schottky gate equivalents are used to construct this high-performance sequencer. The 'AS890 can generate an address and provide register status in only 29 ns while typically requiring only 1.8 watts of power. All internal STL logic in these devices operates on a 2-volt power supply that must be supplied externally. The information generated by the internal STL logic is communicated in the rest of the system via 5-volt Advanced Schottky TTL-compatible I/O ports.

The microsequencers select a 14-bit microaddress from one of eight sources to provide the proper microinstruction sequence for bit-slice processor or other microcode based systems. These high-performance devices are capable of addressing 16,384 control store memory locations either sequentially or via conditional branching algorithms. This multiway branching capability, coupled with a nine-word deep FILO (first in, last out) stack, allows the microprogrammer to arrange his code in blocks so that microprograms may be structured in the same fashion as such high-level languages as ALGOL, Pascal, or Ada.

Both polled and real-time interrupt routines are supported by the 'AS890 to enhance system throughput capability. Vectored interrupts may occur during any instruction, including PUSHes and POPs.

SN74AS890 . . . GB PACKAGE  
(TOP VIEW)

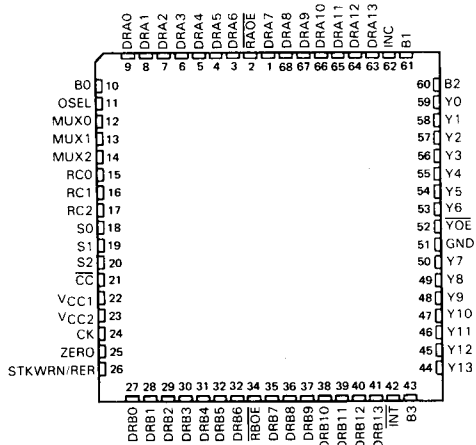


AS890

NO.	PIN	NAME	NO.	PIN	NAME	NO.	PIN	NAME
A-2	DRB10	B-9	STKWRN/RER	F-10	VCC1	K-4	DRA13	
A-3	DRB9	B-10	ZERO	F-11	MUX2	K-5	DRA11	
A-4	DRB8	B-11	CK	G-1	Y5	K-6	DRA8	
A-5	DRB7	C-1	Y13	G-2	Y0E	K-7	DRA7	
A-6	DRB6	C-2	Y10	G-10	RC1	K-8	DRA0	
A-7	DRB5	C-10	CC	G-11	MUX1	K-9	DRA1	
A-8	DRB4	C-11	S1	H-1	Y4	K-10	DRA3	
A-9	DRB3	D-1	Y12	H-2	Y6	K-11	DRA2	
A-10	DRB1	D-2	Y9	H-10	B0	L-2	B2	
B-1	DRB13	D-10	S2	H-11	MUX0	L-3	INC	
B-2	INT	D-11	S0	J-1	Y3	L-4	DRA12	
B-3	DRB12	E-1	Y11	J-2	Y2	L-5	DRA10	
B-4	DRB11	E-2	Y8	J-10	RC2	L-6	DRA9	
B-5	B3	E-10	VCC2	J-11	OSEL	L-7	Y0E	
B-6	RBOE	E-11	RC0	K-1	Y1	L-8	DRA6	
B-7	DRB2	F-1	Y7	K-2	Y0	L-9	DRA5	
B-8	DRB0	F-2	GND	K-3	B1	L-10	DRA4	

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SN74AS890 . . . FN PACKAGE  
(TOP VIEW)



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**TEXAS  
INSTRUMENTS**

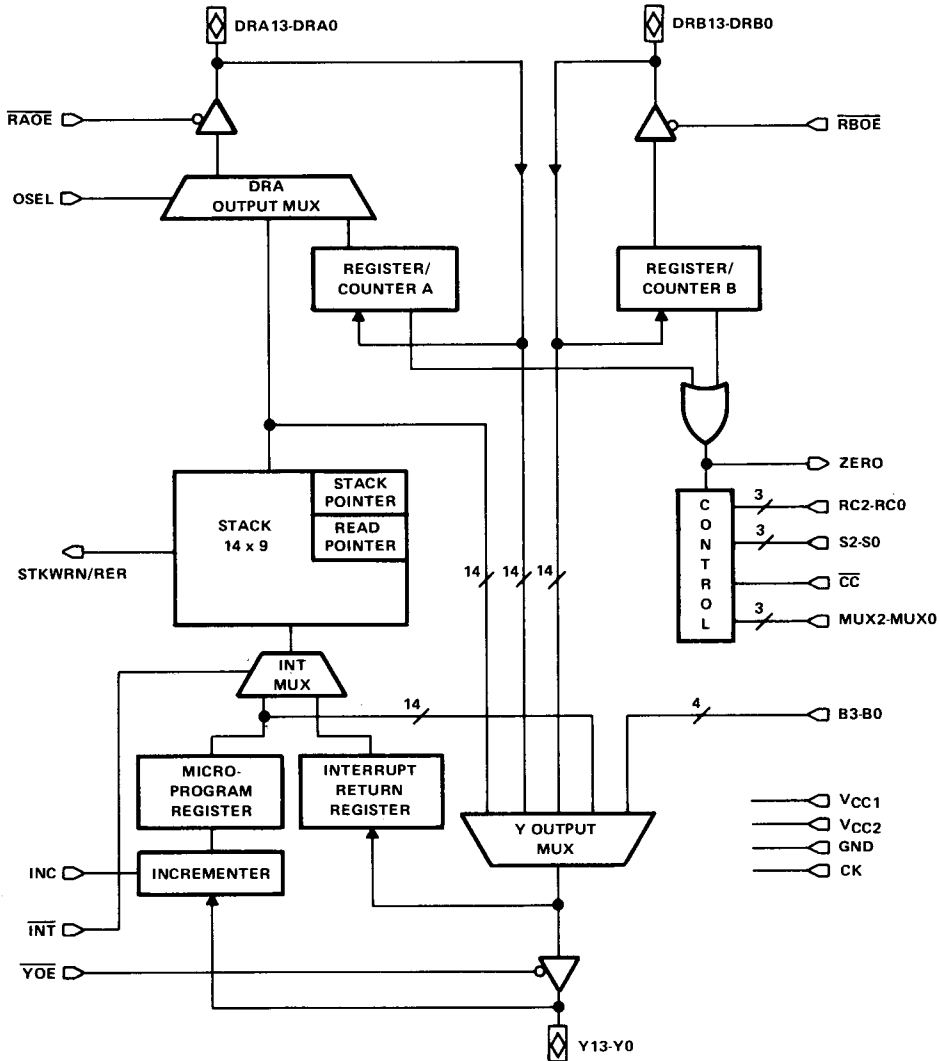
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functional block diagram



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pin descriptions

PIN NAME	I/O	PIN FUNCTION
$\overline{RAOE}$	In	Enables DRA output, active low
DRA6-DRA0	In/Out	Seven LSBs of the A direct data I/O port
OSEL	In	MUX control for the source to DRA. Low selects RA, high selects stack.
MUX2-MUX0	In	MUX control for Y output bus (see Table 1)
RC2-RC0	In	Register/counter controls (see Table 3)
S2-S0	In	Stack control (see Table 2)
CC	In	Condition code
VCC1		5-volt supply for TTL compatible I/O
VCC2		2-volt supply for internal STL
CK	In	Clock
ZERO	Out	Zero detect flag for register A and B
STKWRN/RER	Out	Stack overflow, underflow/read error flag
DRB6-DRB0	In/Out	Seven LSBs of the B direct data I/O port (0 = LSB)
$\overline{RBOE}$	In	Enables DRB output, active low
DRB13-DRB7	In/Out	Seven MSBs of the B direct data I/O port
$\overline{INT}$	In	Active low selects INT RT register to stack
Y13-Y8	In/Out	Six MSBs of bidirectional Y port
GND		Ground
Y7	In/Out	Seventh bit of bidirectional Y port
$\overline{YOE}$	In	Enables Y output bus, active low
Y6-Y0	In/Out	Seven LSBs of bidirectional Y port (0 = LSB)
INC	In	Incrementer control
DRA13-DRA7	In/Out	Seven MSBs of direct B data I/O port
B3-B0	In	16-way branch inputs on

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description (continued)

Two 14-bit loadable registers/counters may be used for temporary storage of data or utilized as down counters for repetitive instructions such as multiplication and division or as loop counters when iterative routines are required

An additional feature is a 24-bit port that appends four user-definable bits to the DRA or DRB address value for support of 16-way branches for the execution of relative branch addressing schemes.

Y output multiplexer

The Y output multiplexer of the 'AS890 is capable of selecting the next branch address from one of eight locations. Addresses may be sourced from:

1. The top of the 14-bit by 9-word address stack
2. An external input on the DRA port, potentially a pipeline register
3. An external input on the DRB port, potentially a pipeline register
4. Internal register/counter A
5. Internal register/counter B
6. An internal microprogram counter (MPC register)
7. An external input onto the bidirectional Y output port
8. A 16-way branch—4 bits appended to DRA, DRB, register/counter A or register/counter B.

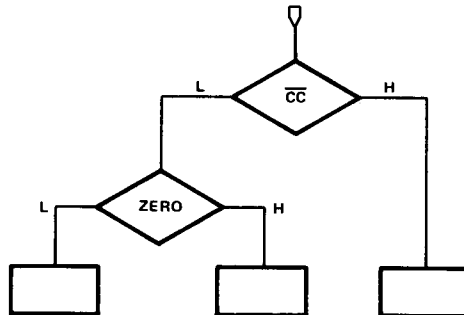
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The source of the next address is dependent upon the previous state of the microsequencer, the MUX controls (MUX2-MUX0), the condition code ( $\overline{CC}$ ) input, and the state of an internal status flag (status externally available at the ZERO output) that indicates that one of the on-chip registers is being decremented to zero.

The entire instruction set may be made conditional by manipulation of the condition code ( $\overline{CC}$ ) input. Allowing the  $\overline{CC}$  value to vary as a result of data or status provides for state-dependent or data-dependent branching. Unconditional branches may be achieved by forcing  $\overline{CC}$  high when selecting control store addresses. Holding this pin low will provide for conditional or unconditional branches as dictated by the state of the zero-detect flag. The required control signals for selection of the Y output source are listed in Table 1. Note that the dependence of the 'AS890 on two variables for conditional branches and jumps allows a conditional branch or conditional jump to subroutine in any clock cycle. Also note that all multiplexer inputs are overridden when all of the stack control inputs are pulled low. This instruction resets the stack and read pointers to zero and places all lines of the Y output bus at the low level.

TABLE 1. Y OUTPUT CONTROL

MUX CONTROL			RESET*	Y OUTPUT SOURCE		Y OUTPUT SOURCE
MUX2	MUX1	MUX0		$\overline{CC} = L$		$\overline{CC} = H$
				ZERO = L	ZERO = H	
X	X	X	YES	ALL LOW	ALL LOW	ALL LOW
L	L	L	NO	STK	MPC	DRA
L	L	H	NO	STK	MPC	DRB
L	H	L	NO	STK	DRA	MPC
L	H	H	NO	STK	DRB	MPC
H	L	L	NO	DRA	MPC	DRB
H	L	H	NO	DRA' (16-WAY BRANCH)	MPC	DRB' (16-WAY BRANCH)
H	H	L	NO	DRA	STK	MPC
H	H	H	NO	DRB	STK	MPC



H = high level, L = low level, X = irrelevant.

\*Reset command is implemented by setting S2-S0 = LLL.

14-bit by 9-word address stack

The positive-edge-triggered 14-bit address stack supplies on-board storage of nine control store addresses that support up to nine nested levels of microsubroutine, looping, and real-time interrupt functions. The stack pointer (SP), which operates as an up-down counter, is updated after the execution of each PUSH operation and before each POP. In a PUSH operation, the address stored in the MPC register is loaded into the stack location addressed by the stack pointer, and the stack pointer is incremented. This address is available at the DRA port by enabling DRA (RAOE low and OSEL high).

A POP operation causes the stack pointer to be decremented on the first rising clock edge following the arrival of the POP instruction at the S2-S0 pins. The value that was indexed by the stack pointer is effectively removed from the top of the stack. All PUSH and POP instructions are conditionally dependent upon the stack control inputs (S2-S0), the condition code ( $\overline{CC}$ ), the input value, and the zero-detect status. The desired option may be selected using the stack control inputs listed in Table 2.

TABLE 2. STACK CONTROL

STACK CONTROL			STACK OPERATION, $\overline{CC} = L$			
S2	S1	S0	OSEL	ZERO = L	ZERO = H	$\overline{CC} = H$
L	L	L	X	RESET/CLEAR	RESET/CLEAR	RESET/CLEAR
L	L	H	X	CLEAR SP, RP	HOLD	HOLD
L	H	L	X	HOLD	POP	POP
L	H	H	X	POP	HOLD	HOLD
H	L	L	X	HOLD	PUSH	PUSH
H	L	H	X	PUSH	HOLD	HOLD
H	H	L	X	PUSH	HOLD	PUSH
H	H	H	H	READ	READ	READ
H	H	H	L	HOLD	HOLD	HOLD

The read pointer (RP) is a useful tool in debugging microcoded systems. A microprogrammer now has the ability to perform a nondestructive, sequential read of the stack contents from the DRA port. This capability provides the user with a method of backtracking through the address sequence to determine the cause of overflow without affecting program flow, the status of the stack-pointer or the internal data of the stack. Placing a high value on all of the stack inputs (S2-S0) and OSEL places the 'AS890 into the read mode. At each low-to-high clock transition, the value pointed to by the read pointer is available at the DRA port and the read pointer is decremented. Microcode diagnostics are simplified by the ability of the 'AS890 to sequentially dump the contents of its stack. The bottom of the stack is detected by monitoring the STKW RN/RER (stack warning/read error) pin. A high will appear when the stack contains one word and a READ instruction is applied to the S2-S0 pins. This signifies that the last address has been read. The stack pointer and stack contents are unaffected by the READ operation. Under normal PUSH and POP operations the read pointer is updated with the stack pointer and contains identical information.

The STKW RN/RER pin alerts the system to a potential stack overflow or underflow condition. STKW RN/RER becomes active under two additional conditions. If seven of the nine stack locations (0-8) are full (the stack pointer is at 7) and a PUSH occurs, the STKW RN/RER pin will produce a high-level signal to warn that the stack is approaching its capacity, and will be full after one more PUSH. Knowledge that overflow potential exists allows bit-slice-based systems to continuously process real-time interrupt vectors. This signal will remain high, if HOLD, PUSH, or POP instructions occur, until the stack pointer is decremented to 7.

The user may be protected from attempting to POP an empty stack by monitoring STKW RN/RER before POP operations. A high level at this pin signifies that the last address has been removed from the stack (SP=0). This condition remains until an address is pushed onto the stack and the stack pointer is incremented to one.

Clearing the stack and read pointer is accomplished by placing low levels onto the stack control lines (S2-S0). This function overrides all of the Y output MUX controls and places the Y bus into a low state.

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**register/counters**

Two loadable 14-bit registers extend the looping and branching capabilities. Addresses may be loaded directly into register/counter A (RA) and register/counter B (RB) through the direct data ports DRA13-DRA0 and DRB13-DRB0. The values stored in these registers may either be held, decremented, or read as a result of the register control inputs (RC2-RC0),  $\overline{RAOE}$ , and  $\overline{RBOE}$ . All combinations of these functions are supported with the exception of a simultaneous decrement of both registers. Generation of iteration routines may be accomplished by loading RA and/or RB and operating them as a down counter. Loop termination is acknowledged by the ZERO output going high to indicate that a register contains a binary one and that a decrement is about to take place. Because of this facility, a "decrement and branch on loop" termination may be executed in the same clock cycle.

The contents of RA are accessible to the DRA port when OSEL is low and the output bus is enabled by  $\overline{RAOE}$  being low. Data from RB is available when DRB is enabled by  $\overline{RBOE}$  being low. Note that control of the registers is maintained while an external value is active on the DRA and DRB ports. A value being directed from the DRA and DRB buses to the output will not inhibit the decrement operation.

Register/counter controls are listed in Table 3.

**TABLE 3. REGISTER CONTROL**

RC2	RC1	RC0	REG A	REG B
L	L	L	HOLD	HOLD
L	L	H	DEC	HOLD
L	H	L	LOAD	HOLD
L	H	H	DEC	LOAD
H	L	L	LOAD	LOAD
H	L	H	HOLD	DEC
H	H	L	HOLD	LOAD
H	H	H	LOAD	DEC

**microprogram register and increment**

The microprogram register (MPC) and the incremter (INC) provide the means for generating the next microprogram address for sequential addressing operations. The MPC may be loaded with either the outgoing address on the Y bus or may receive an external address for processing interrupt vectors.

The current address on the Y bus is passed to the MPC at each rising clock edge, either unaltered (INC low) for repeating statements, or incremented by one (INC high) for addressing sequential control store locations.

The MPC may also be externally loaded for subroutine and interrupt functions. Taking  $\overline{YOE}$  high and forcing the new address onto the bidirectional Y bus loads the MPC with the new address at the positive clock edge. This value may also be incremented prior to storage in the MPC for sequential addressing of subroutines or interrupt routines.

**interrupts**

Real-time vectored interrupt routines are supported for those applications where polling would impede system throughput. Any instruction, including PUSHes and POPs, may be interrupted. To process an interrupt, the following procedure should be followed:

1. The bidirectional Y bus is placed into the high-impedance state by forcing  $\overline{YOE}$  high.
2. The interrupt entry point vector is then forced onto the Y bus and incremented to become the second microinstruction of the interrupt routine. This is accomplished by making INC high.

3. At the following clock edge, the second microaddress is stored in the MPC and the interrupted address will be stored in the INT RT register which always contains the outgoing value on the Y bus. This edge also causes the processor to begin execution of the first instruction of the interrupt routine. This first instruction must PUSH the address stored in the INT RT register onto the stack so that the proper return linkage is maintained. This is accomplished by making INT low and performing a PUSH. If this instruction were to be interrupted, the process would be repeated and the proper return linkage preserved.

**control inputs**

A listing of the response of internal elements to various control inputs is given in Table 4.

**TABLE 4. RESPONSE TO CONTROL INPUTS**

PIN NAME	LOGIC LEVEL	
	HIGH	LOW
RAOE	DRA output in high-Z state	DRA output is active
RBOE	DRB output in high-Z state	DRB output is active
YOE	Y output in high-Z state	Y output is active
INT	MPC to stack	INT RT register to stack
OSEL	Stack to DRA buffer input	RA to DRA buffer input
INC	Adds one to Y output and stores in MPC	Passes Y output to MPC unaltered
MUX2-MUX0	Table 1	Table 1
S2-S0	Table 2	Table 2
RC2-RC0	Table 3	Table 3

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**instruction set**

Sixty-four microsequencing instructions enable the 'AS890 to generate micro-addresses for up to 16,384 locations. Any instruction can be made conditional depending upon the value of the externally applied condition code (CC) and the value stored in either of the internal register/counters.

The required signals for selection of the Y output source were listed in Table 1. Suggested methods for implementing a few commonly used instructions are given in Table 5 and flowcharts showing execution examples are illustrated in Figure 1.

It should be noted that the term jump refers to a subroutine call that must be accompanied by a return instruction. The term branch implies that a deviation from the program flow is accomplished but no return is required.

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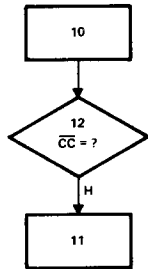
**TABLE 5. SUGGESTED CODING FOR REPRESENTATIVE INSTRUCTIONS**

FUNCTION	MNEMONIC	MUX2	MUX1	MUX0	S2	S1	S0	CC	FIGURE
Continue	CONT	X	H	X	H	H	H	H	1(a)
Unconditional branch	BR	L	L	X	H	H	H	H	1(b)
Conditional branch	CBR	H	H	X	H	H	H	V	1(c)
Three-way branch	BR2W	H	L	L	H	H	H	V	1(d)
Conditional loop on stack	LOOPS	L	L	X	L	H	L	L	1(e)
Repeat	REPEAT	L	L	X	H	H	H	L	1(f)
Loop on stack with exit	LSWE	L	L	X	L	H	L	V	1(g)
Conditional jump to subroutine	CJSR	H	H	X	H	L	H	V	1(h)
Jump to subroutine	JSR	L	L	X	H	L	H	H	1(i)
Two-way jump to subroutine	JSR2W	H	L	L	H	H	L	V	1(j)
Repeat until	UNTIL	L	H	X	L	H	L	V	1(k)
Return from subroutine	RTS	L	H	X	L	H	H	L	1(l)
Conditional return from subroutine	CRTS	L	H	X	L	H	H	V	1(m)
Conditional return from subroutine or branch	CRTSB	L	H	X	L	H	H	V	1(n)
Conditional branch and PUSH	CBRP	H	H	X	H	L	H	V	1(o)
Conditional branch and POP	CBRPO	H	H	X	L	H	H	V	1(p)
PUSH and continue	PUSH	L	H	X	H	L	L	H	1(q)
POP and continue	POP	X	H	X	L	H	L	H	1(r)
Exit from loop	EXITLP	L	L	X	L	H	L	V	1(s)
Reset and clear stack/read pointer	RESET	X	X	X	L	L	L	X	1(t)
32-way branch	BR32W	H	L	H	H	H	H	V	1(u)
Execute n times	NEX	L	L	X	L	H	L	L	1(v)

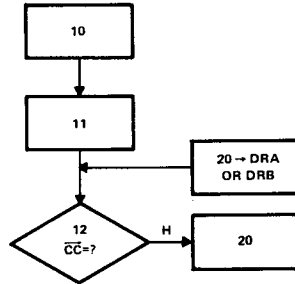
H = high level, L = low level, X = irrelevant, V = varies (condition code value is dependent upon machine and data status and will vary accordingly).

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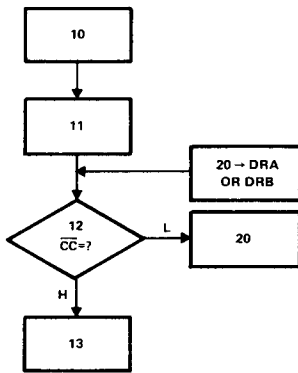




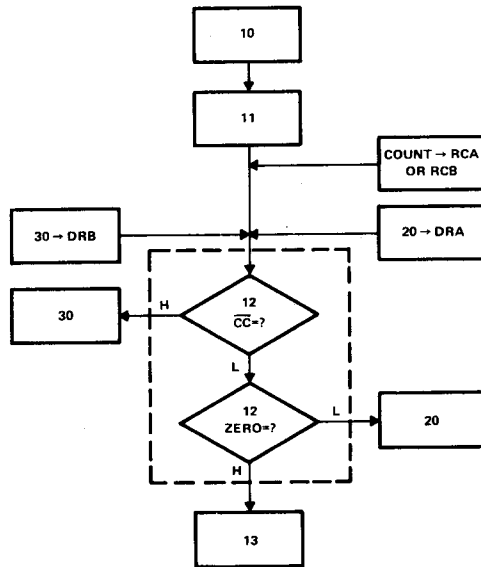
(a) CONTINUE  
(CC FORCED)



(b) UNCONDITIONAL BRANCH  
(CC FORCED)



(c) CONDITIONAL BRANCH  
(DEC DISABLED)

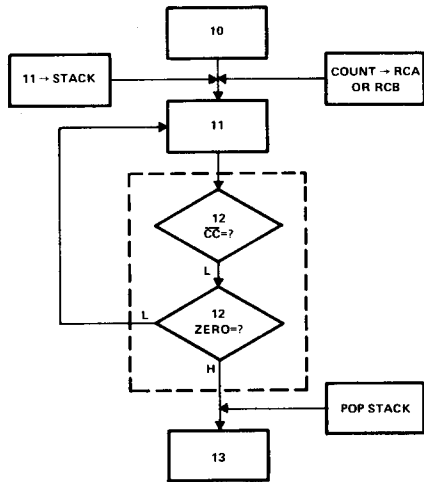


(d) THREE-WAY BRANCH (DEC ENABLED)<sup>1</sup>

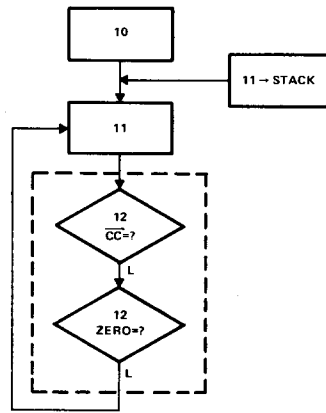
NOTE 1:  $\overline{CC}$  and ZERO are completed in the same clock cycle.

FIGURE 1. INSTRUCTION SET FLOWCHARTS

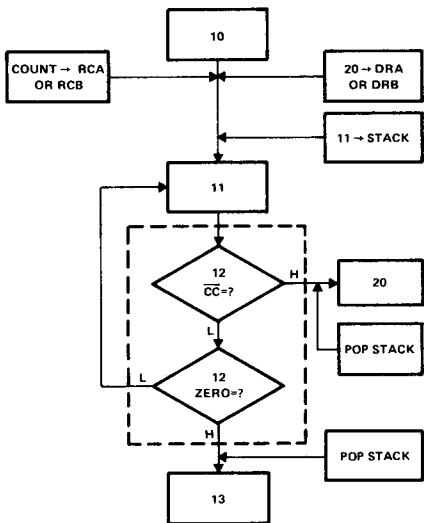
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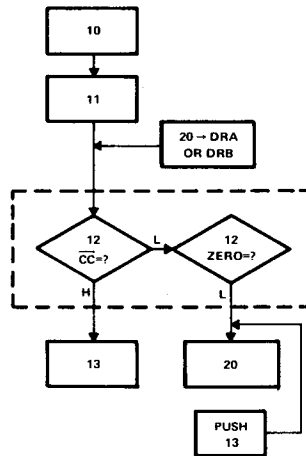
(e) CONDITIONAL LOOP ON STACK  
(CC FORCED, DEC ENABLED)<sup>1</sup>



(f) REPEAT ( $\overline{CC}$  FORCED, DEC DISABLED)<sup>1</sup>



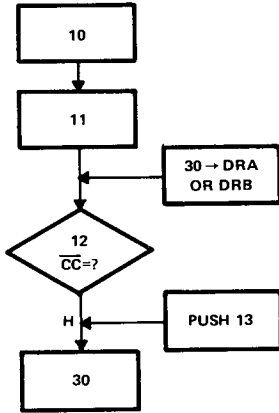
(g) CONDITIONAL LOOP ON STACK  
WITH EXIT (DEC ENABLED)<sup>1</sup>



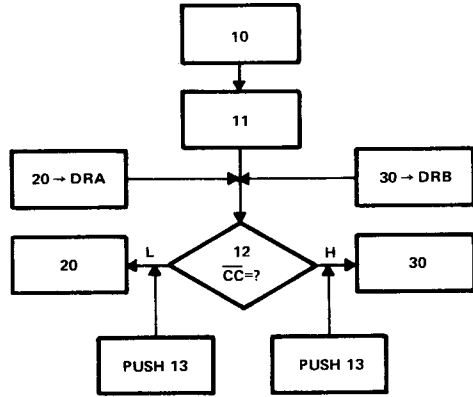
(h) CONDITIONAL JUMP TO SUBROUTINE  
(DEC DISABLED)<sup>1</sup>

NOTE 1:  $\overline{CC}$  and ZERO are completed in the same clock cycle.

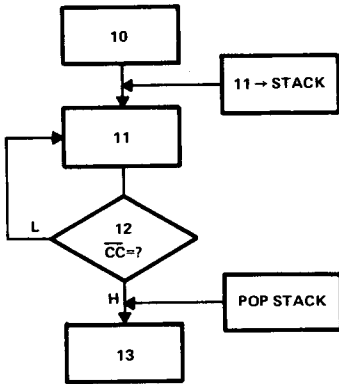
FIGURE 1. INSTRUCTION SET FLOWCHARTS (continued)



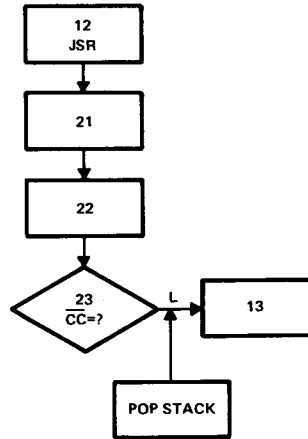
(i) JUMP TO SUBROUTINE  
( $\overline{CC}$  FORCED)



(j) TWO-WAY JUMP TO SUBROUTINE  
(DEC DISABLED)



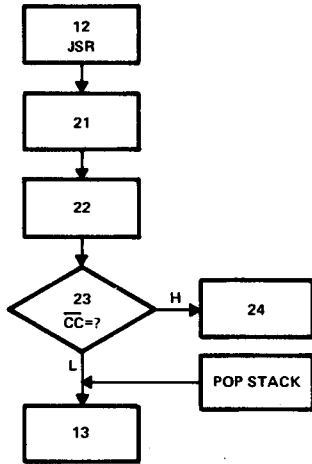
(k) REPEAT UNTIL  
(DEC DISABLED)



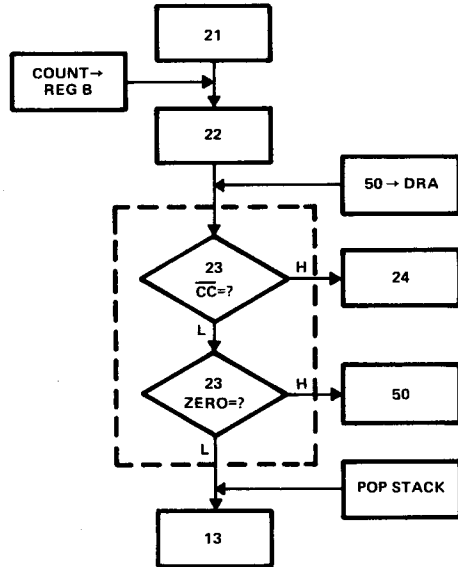
(l) RETURN FROM SUBROUTINE  
( $\overline{CC}$  FORCED, DEC DISABLED)

FIGURE 1. INSTRUCTION SET FLOWCHARTS (continued)

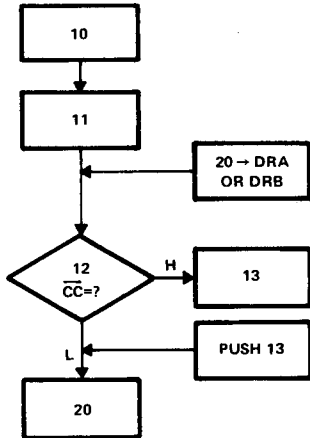
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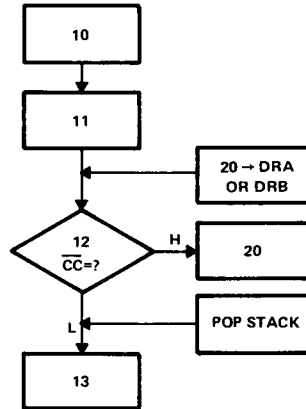
(m) CONDITIONAL RETURN FROM SUBROUTINE FROM SUBROUTINE (DEC DISABLED)



(n) CONDITIONAL RETURN FROM SUBROUTINE OR BRANCH (DEC ENABLED)<sup>1</sup>



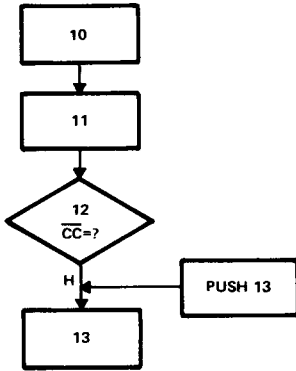
(o) CONDITIONAL BRANCH AND PUSH (DEC DISABLED)



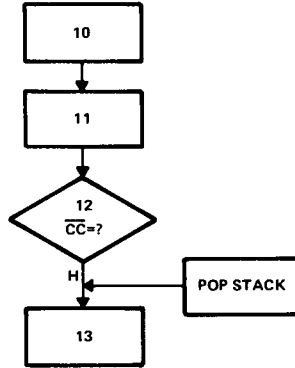
(p) CONDITIONAL BRANCH AND POP (DEC DISABLED)

NOTE 1:  $\overline{CC}$  and ZERO are completed in the same clock cycle.

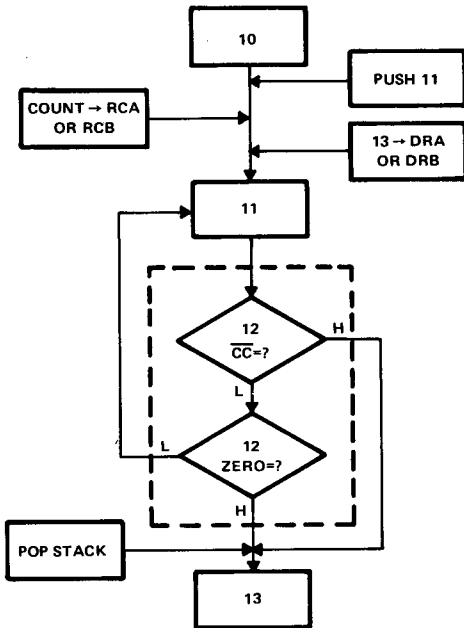
FIGURE 1. INSTRUCTION SET FLOWCHARTS (continued)



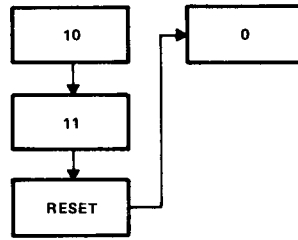
(q) PUSH AND CONTINUE  
( $\overline{CC}$  FORCED)



(r) POP AND CONTINUE  
( $\overline{CC}$  FORCED)



(s) EXIT FROM LOOP  
(DEC ENABLED)<sup>†</sup>



(t) RESET AND CLEAR

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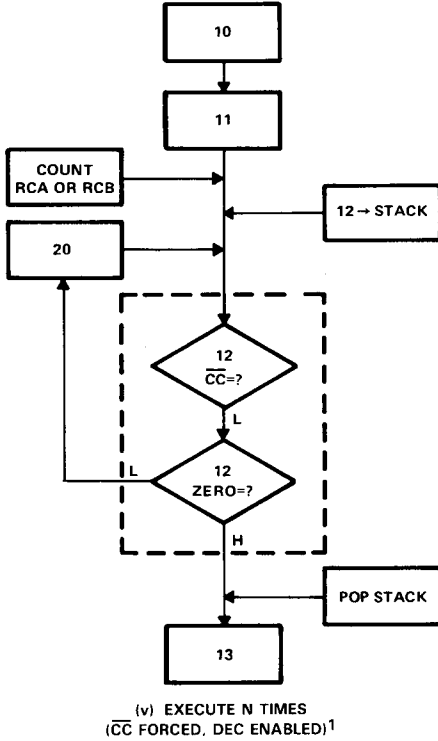
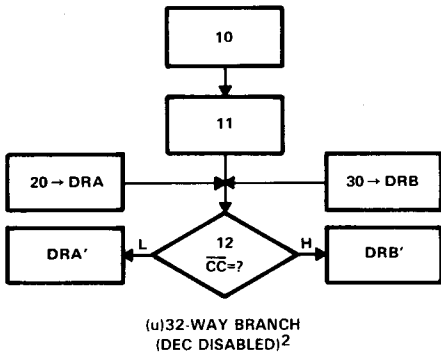
NOTE 1:  $\overline{CC}$  and ZERO are completed in the same clock cycle.

FIGURE 1. INSTRUCTION SET FLOWCHARTS (continued)

**SN54AS890, SN74AS890  
MICROSEQUENCERS**

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- NOTES: 1.  $\overline{CC}$  and ZERO are completed in the same clock cycle.  
 2. The least significant four bits, DRA and DRB, will be stripped off and four new bits appended to them from the B3-B0 port.

**FIGURE 1. INSTRUCTION SET FLOWCHARTS (concluded)**

# SN54AS890, SN74AS890 MICROSEQUENCERS

## absolute maximum ratings over operating temperature range (unless otherwise noted)

Supply voltage, $V_{CC1}$ .....	7 V
Supply voltage, $V_{CC2}$ .....	3 V
Input voltage: All inputs .....	7 V
I/O ports .....	5.5 V
Operating case temperature range, SN54AS890 .....	-55°C to 125°C
Operating free-air temperature range, SN74AS890 .....	0°C to 70°C
Storage temperature range .....	-65°C to 150°C

## recommended operating conditions

		SN54AS890			SN74AS890			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX		
$V_{CC1}$	I/O supply voltage	4.5	5	5.5	4.5	5	5.5	V	
$V_{CC2}$	STL internal logic supply voltage	1.9	2	2.1	1.9	2	2.1	V	
$V_{IH}$	High-level input voltage	2			2			V	
$V_{IL}$	Low-level input voltage				0.8			V	
$I_{OH}$	High-level output current				-1			mA	
$I_{OL}$	Low-level output current	All outputs except Y13-Y0			8			mA	
		Y13-Y0			12				
$T_C$	Operating case temperature	-55			125			°C	
$T_A$	Operating free air temperature				0			70	°C

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## electrical characteristics over recommended operating temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54AS890			SN74AS890			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
$V_{IK}$		$V_{CC1} = 4.5$ V,	$I_I = -18$ mA	-1.2			-1.2			V
$V_{OH}$		$V_{CC1} = 4.5$ V to 5.5 V,	$I_{OH} = -0.4$ mA	$V_{CC} - 2$			$V_{CC} - 2$			V
		$V_{CC1} = 4.5$ V,	$I_{OH} = -1$ mA	2.4			3.4			
		$V_{CC1} = 4.5$ V,	$I_{OH} = -2.6$ mA				2.4			
$V_{OL}$	All outputs except Y13-Y0	$V_{CC1} = 4.5$ V,	$I_{OL} = 8$ mA	0.5			0.5			V
	Y13-Y0	$V_{CC1} = 4.5$ V,	$I_{OL} = 12$ mA	0.5			0.5			
$I_I$	Inputs	$V_{CC1} = 5.5$ V,	$V_I = 7$ V	0.1			0.1			mA
	I/O ports	$V_{CC1} = 5.5$ V,	$V_I = 5.5$ V	0.1			0.1			
$I_{IH}$	Inputs	$V_{CC1} = 5.5$ V,	$V_I = 2.7$ V	20			20			µA
	I/O ports‡			40			40			
$I_{IL}$ ‡		$V_{CC1} = 5.5$ V,	$V_I = 0.4$ V	-0.4			-0.4			mA
$I_O$ §		$V_{CC1} = 5.5$ V,	$V_O = 2.25$ V	-30			-112			mA
$I_{CC1}$		$V_{CC1} = 5.5$ V		185			178			mA
$I_{CC2}$		$V_{CC2} = 2.1$ V		420			400			mA

† All typical values are at  $V_{CC} = 5$  V,  $T_A = 25$ °C.

‡ For I/O ports, the parameters  $I_{IH}$  and  $I_{IL}$  include output current  $I_{OZL}$  and  $I_{OZL}$ , respectively.

§ The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit current,  $I_{OS}$ .

# SN54AS890 MICROSEQUENCERS

SN54AS890 maximum switching characteristics:  $V_{CC1} = 4.5\text{ V to }5.5\text{ V}$ ,  $V_{CC2} = 1.9\text{ V to }2.1\text{ V}$ ,  
 $T_C = 55^\circ\text{C to }125^\circ\text{C}$  (see Note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)					UNIT
		Y	ZERO	DRA	DRB	STKWRN	
$t_{pd}$	$\overline{CC}$	32					ns
	CK	32		30	30	30	
	DRA13-DRA0	53 <sup>†</sup>	42 <sup>†</sup>				
	DRB13-DRB0	16					
	MUX2-MUX0	16					
	RC2-RC0	36					
	S2-S0	32	14				
	B2-B0	22					
	OSEL			24			
$t_{en}$	$\overline{YOE}$	16					ns
	$\overline{RAOE}$			16			
	$\overline{RBOE}$				16		
$t_{dis}$	$\overline{YOE}$	16					ns
	$\overline{RAOE}$			16			
	$\overline{RBOE}$				16		

<sup>†</sup> Decrementing Register/Counter A or B and sensing a zero.

NOTE 2: Load circuit and voltage waveforms are shown in Section 1

## SN54AS890 setup and hold times

PARAMETER	FROM	TO (DESTINATION)	MIN	MAX	UNIT
$t_{su}$	$\overline{CC}$	Stack	10		ns
	DRA13-DRA0	RCA, INT RT	5		
	DRB13-DRB0	RCB, INT RT	5		
	INC	MPC	10		
	$\overline{INT}$	Stack	10		
	RC2-RC0	Stack	16		
		RCA, RCB	10		
		INT RT	14		
	S2-S0	Stack	10		
		INT RT	10		
	MUX2-MUX0	INT RT	14		
B3-B0	INT RT	14			
Y13-Y0	MPC	12			
$t_h$	Any Input	Any Destination	2		

## SN54AS890 minimum clock requirements (see Note 3)

PARAMETER	MIN	MAX	UNIT
$t_{wL}(CK)$ Pulse duration, clock low	10		ns
$t_{wH}(CK)$ Pulse duration, clock high	20		
$t_c(CK)$ Clock cycle time	55 <sup>†</sup>	45	

<sup>†</sup> Decrementing Register/Counter A or B and sensing a zero.

NOTE 3: The total clock period of clock high and clock low must not be less than clock cycle time. The minimum pulse durations specified are only for clock high or clock low, but not for both simultaneously.



**SN74AS890 maximum switching characteristics: VCC1 = 4.5 V to 5.5 V, VCC2 = 1.9 V to 2.1 V, TA = 0°C to 70°C (see Note 2)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)					UNIT
		Y	ZERO	DRA	DRB	STKWRN	
t <sub>pd</sub>	$\overline{CC}$	29					ns
	CK	29		29	29	29	
		50 <sup>†</sup>	39 <sup>†</sup>				
	DRA13-DRA0	15					
	DRB13-DRB0	15					
	MUX2-MUX0	35					
	RC2-RC0	30	13				
	S2-S0	28					
B2-B0	20						
t <sub>en</sub>	OSEL			18			ns
	YOE	15					
	RAOE			15			
t <sub>dis</sub>	RBOE				15		ns
	YOE	16					
	RAOE			16			
	RBOE				16		

<sup>†</sup> Decrementing Register/Counter A or B and sensing a zero.

NOTE 2: Load circuit and voltage waveforms are shown in Section 1.

**SN74AS890 setup and hold times**

PARAMETER	FROM	TO (DESTINATION)	MIN	MAX	UNIT
t <sub>su</sub>	$\overline{CC}$	Stack	10		ns
	DRA13-DRA0	RCA, INT RT	5		
	DRB13-DRB0	RCB, INT RT	5		
	INC	MPC	10		
	INT	Stack	10		
		Stack	14		
	RC2-RC0	RCA, RCB	10		
		INT RT	12		
	S2-S0	Any Destination	10		
	MUX2-MUX0	INT RT	12		
B3-B0	INT RT	14			
Y13-Y0	MPC	10			
t <sub>h</sub>	Any Input	Any Destination	2		

**SN74AS890 minimum clock requirements (see Note 3)**

PARAMETER	MIN	MAX	UNIT
t <sub>wL(CK)</sub> Pulse duration, clock low	10		ns
t <sub>wH(CK)</sub> Pulse duration, clock high	20		
t <sub>c(CK)</sub> Clock cycle time	50 <sup>†</sup>		
	36		

<sup>†</sup> Decrementing Register/Counter A or B and sensing a zero.

NOTE 3: The total clock period of clock high and clock low must not be less than clock cycle time. The minimum pulse durations specified are only for clock high or clock low, but not for both simultaneously.

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# SN74AS890-1 MICROSEQUENCERS

SN74AS890-1 maximum switching characteristics:  $V_{CC1} = 4.5\text{ V to }5.5\text{ V}$ ,  $V_{CC2} = 1.9\text{ V to }2.1\text{ V}$ ,  $T_A = 0^\circ\text{C to }70^\circ\text{C}$  (see Note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)					UNIT
		Y	ZERO	DRA	DRB	STKWRN	
$t_{pd}$	$\overline{CC}$	25					ns
	CK	25		25	25	25	
		42 <sup>†</sup>	34 <sup>†</sup>				
	DRA13-DRA0	14					
	DRB13-DRB0	14					
	MUX2-MUX0	31					
	RC2-RC0	26	12				
	S2-S0	25					
B2-B0	19						
OSEL			17				
$t_{en}$	$\overline{YOE}$	15					ns
	$\overline{RAOE}$			15			
	$\overline{RBOE}$				15		
$t_{dis}$	$\overline{YOE}$	16					ns
	$\overline{RAOE}$			16			
	$\overline{RBOE}$				16		

<sup>†</sup> Decrementing Register/Counter A or B and sensing a zero.

NOTE 2: Load circuit and voltage waveforms are shown in Section 1.

## SN74AS890-1 setup and hold times

PARAMETER	FROM	TO (DESTINATION)	MIN	MAX	UNIT
$t_{su}$	$\overline{CC}$	Stack	10		ns
	DRA13-DRA0	RCA, INT RT	5		
	DRB13-DRB0	RCB, INT RT	5		
	INC	MPC	10		
	INT	Stack	10		
	RC2-RC0	Stack	14		
		RCA, RCB	10		
		INT RT	12		
	S2-S0	Any Destination	10		
	MUX2-MUX0	INT RT	12		
B3-B0	INT RT	14			
Y13-Y0	MPC	10			
$t_h$	Any Input	Any Destination	2		

## SN74AS890-1 minimum clock requirements (see Note 3)

PARAMETER	MIN	MAX	UNIT
$t_{wL}(CK)$ Pulse duration, clock low	10		ns
$t_{wH}(CK)$ Pulse duration, clock high	20		
$t_{c}(CK)$ Clock cycle time	42 <sup>†</sup>		
	34		

<sup>†</sup> Decrementing Register/Counter A or B and sensing a zero.

NOTE 3: The total clock period of clock high and clock low must not be less than clock cycle time. The minimum pulse durations specified are only for clock high or clock low, but not for both simultaneously.